

ABSTRACT

The present invention (first invention) is a pressure-sensitive adhesive tape set including at least one pressure-sensitive adhesive tape for semiconductor wafer fabrication constituted with a first laminate including a sheet-shaped first base material containing a resin material and a first pressure-sensitive adhesive layer laminated on the first base material and at least one pressure-sensitive adhesive tape for semiconductor element transport constituted with a second laminate including a sheet-shaped second base material containing a resin material and a second pressure-sensitive adhesive layer laminated on the second base material, in which a contact angle of hexadecane with respect to the first pressure-sensitive adhesive layer is equal to or greater than 10°, and a contact angle of hexadecane with respect to the second pressure-sensitive adhesive layer is less than 10°.